

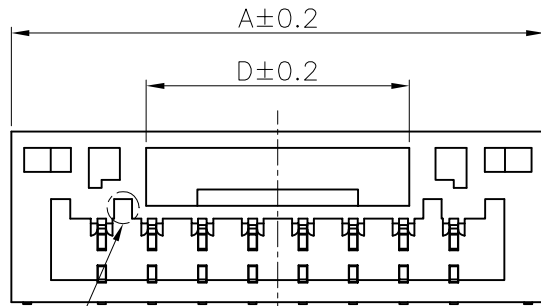
REV.	ECN NO	DESCRIPTION	REVISED	DATE
A		新订图面	HELLER	2017.9.30
B	20211213068	增加焊片焊锡面积及强度	HELLER	2021.12.13

Specifications / 技术规格:

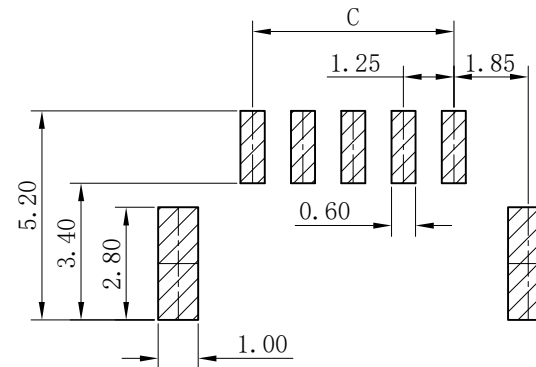
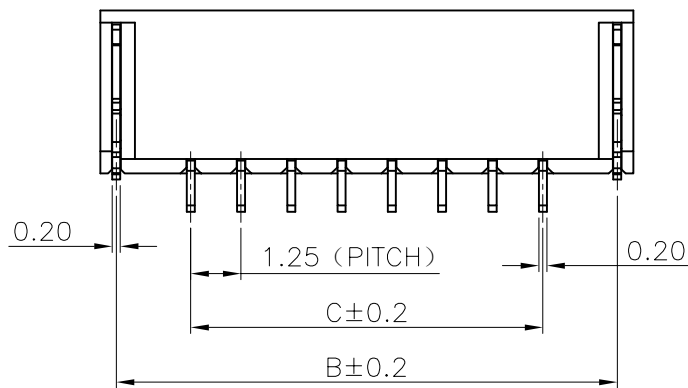
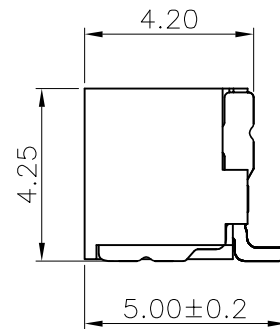
Current rating: 1A
 额定电流: 1A
 Voltage rating: 50V AC, DC
 额定电压: 50V AC, DC
 Insulation Resistance: 500MΩ Min.
 绝缘电阻: 最小500MΩ
 Dielectric Withstanding: 500V AC 1Min
 耐电压: 500V AC 1分钟
 Contact Resistance: 20mΩ Max.
 接触电阻: 最大20mΩ
 Operating Temperature: -25°C to +85°C
 工作温度: -25°C 到85°C

Materials / 材料:

Contact/Soldering Material: Phos.bronze (Tin plating)
 接触端子/焊片材料: 磷铜(镀锡)
 Insulation Material: LCP or PA UL94 V-0
 绝缘体塑胶材质: LCP 或 PA UL94 V-0



2-7PIN无此槽, 8-13PIN有槽, 14PIN以上此槽向中心移1.25mm



Recommended P.C.Board Layout

PIN 数	DIM			
	A	B	C	D
2	5.75	4.95	1.25	2.20
3	7.00	6.20	2.50	3.30
4	8.25	7.45	3.75	4.55
5	9.50	8.70	5.00	
6	10.75	9.95	6.25	6.55
7	12.00	11.20	7.50	
8	13.25	12.45	8.75	
9	14.50	13.70	10.00	8.55
10	15.75	14.95	11.25	
11	17.00	16.20	12.50	
12	18.25	17.45	13.75	
13	19.50	18.70	15.00	
14	20.75	19.95	16.25	
15	22.00	21.20	17.50	
16	23.25	22.45	18.75	
17	24.50	23.70	20.00	
18	25.75	24.95	21.25	
19	27.00	26.20	22.50	
20	28.25	27.45	23.75	

浙江快利电子有限公司
 Zhejiang Kuaili Electronic Co., Ltd

GENERAL TOLERANCE

X.* ± 3'	.XXX : ±0.10
.X* ± 2'	.XX : ±0.15
.XX* ± 1'	.X : ±0.25
.XXX* ± 0.5'	X. : ±0.35

DESIGN: HELLER

DATE: 2012.12.13

DWG. NO.

TITLE.

AUDITED: 朱建慧

DATE: 2012.12.13

PART NO.

GH-NAWT 卧贴

APPROVED: 朱建华

DATE: 2012.12.13

KL-GH-NAWT

REV.	B	UNIT.	MM	SCALE.	1:1